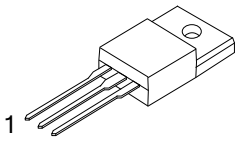
4A, 650V N-CHANNEL POWER MOSFET



TO-220F

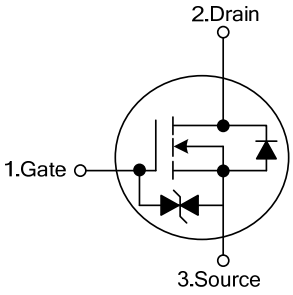
■ DESCRIPTION

The UTC **4N65Z** is a high voltage power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristic. This power MOSFET is usually used in high speed switching applications including power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

■ FEATURES

* $R_{DS(ON)}$ < 2.5Ω @ V_{GS} = 10 V, I_D = 2.2A
* Ultra Low Gate Charge (typical 15 nC)
* Low Reverse Transfer Capacitance (C_{RSS} = Typical 8.0 pF)
* Fast Switching Capability
* Avalanche Energy Specified
* Improved dv/dt Capability, High Ruggedness

■ SYMBOL



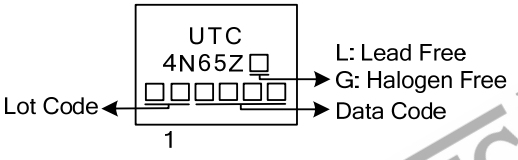
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
4N65ZL- TF3-T	4N65ZG-TF3-T	TO-220F	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

4N65ZL-TF3-T (1)Packing Type (2)Package Type (3)Green Package	(1) T: Tube (2) TF3: TO-22F (3) L: Lead Free, G: Halogen Free and Lead Free

■ MARKING



■ ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±20	V
Avalanche Current (Note 2)		I_{AR}	4.4	A
Drain Current	Continuous	I_D	4.0	A
	Pulsed (Note 2)	I_{DM}	16	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	260	mJ
	Repetitive (Note 2)	E_{AR}	10.6	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation		P_D	36	W
Junction Temperature		T_J	+150	°C
Operating Temperature		T_{OPR}	-55 ~ +150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature
3. L = 30mH, I_{AS} = 4A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
4. I_{SD}≤4.4A, di/dt ≤200A/μs, V_{DD}≤BV_{DSS}, Starting T_J = 25°C

■ THERMAL DATA

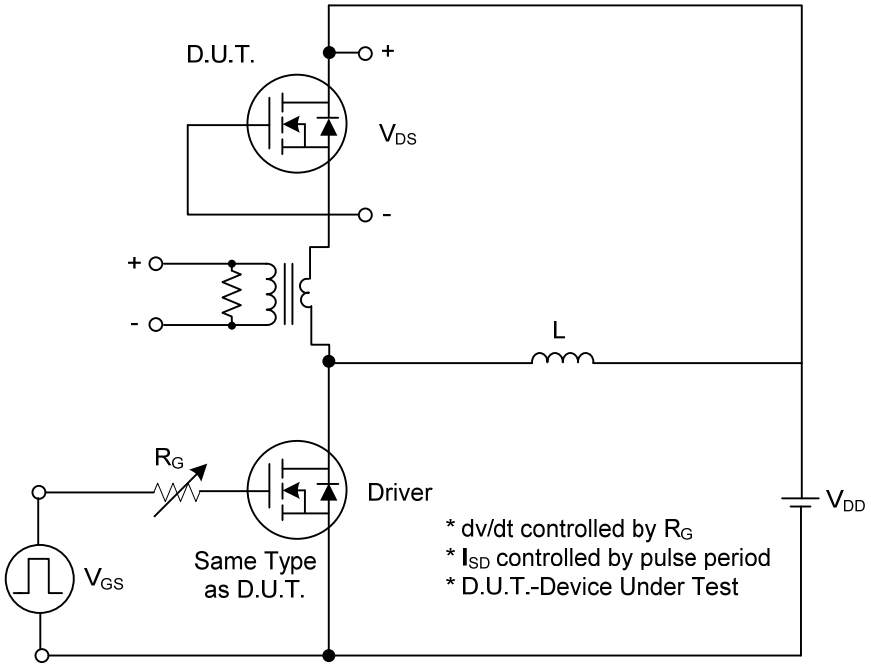
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	62.5	°C/W
Junction to Case	θ_{Jc}	3.47	°C/W

■ ELECTRICAL CHARACTERISTICS (T_C =25°C, unless otherwise specified)

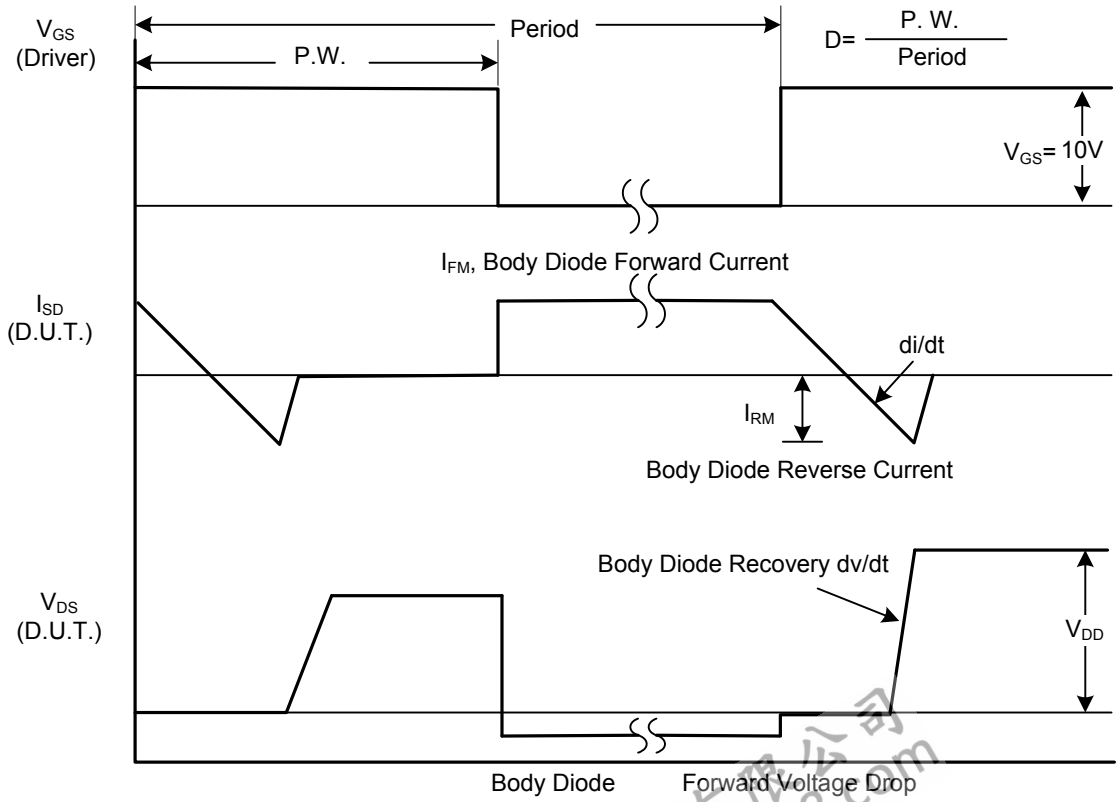
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS} = 0 V, I_D = 250μA	650			V
Drain-Source Leakage Current		I_{DSS}	V_{DS} = 650 V, V_{GS} = 0 V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS} = 20 V, V_{DS} = 0 V			5	μA
	Reverse		V_{GS} = -20 V, V_{DS} = 0 V			-5	μA
Breakdown Voltage Temperature Coefficient		$\triangle BV_{DSS}/\triangle T_J$	I_D=250μA, Referenced to 25°C		0.6		V/°C
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS} = V_{GS}, I_D = 250μA	2.0		4.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS} = 10 V, I_D = 2.2A		2.4	2.5	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{ISS}	V_{DS} = 25 V, V_{GS} = 0V, f = 1MHz		520	670	pF
Output Capacitance		C_{OSS}			70	90	pF
Reverse Transfer Capacitance		C_{RSS}			8	11	pF
SWITCHING CHARACTERISTICS							
Total Gate Charge		Q_G	V_{DS}= 520V,I_D= 4.0A, V_{GS}= 10V (Note 1, 2)		15	20	nC
Gate-Source Charge		Q_{GS}			3.4		nC
Gate-Drain Charge		Q_{GD}			7.1		nC
Turn-On Delay Time		$t_{D(ON)}$	V_{DD} = 325V, I_D = 4.0A, R_G = 25Ω (Note 1, 2)		13	35	ns
Turn-On Rise Time		t_R			45	100	ns
Turn-Off Delay Time		$t_{D(OFF)}$			25	60	ns
Turn-Off Fall Time		t_F			35	80	ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Drain-Source Diode Forward Voltage		V_{SD}	V_{GS} = 0 V, I_S = 4.4A			1.4	V
Maximum Continuous Drain-Source Diode Forward Current		I_S				4.4	A
Maximum Pulsed Drain-Source Diode Forward Current		I_{SM}				17.6	A
Reverse Recovery Time		t_{rr}	V_{GS} = 0V, I_S = 4.4A, dI_F/dt = 100 A/μs (Note 1)		250		ns
Reverse Recovery Charge		Q_{RR}			1.5		μC

Note: 1. Pulse Test: Pulse width≤300μs, Duty cycle≤2%
2. Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

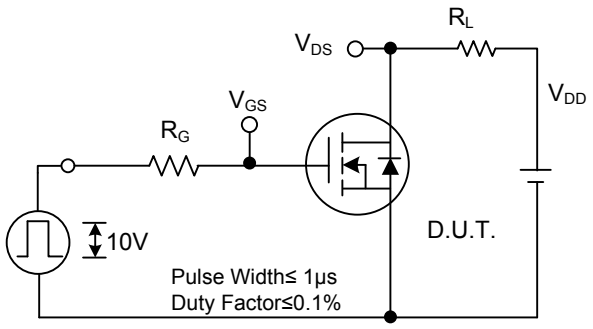


Peak Diode Recovery dv/dt Test Circuit

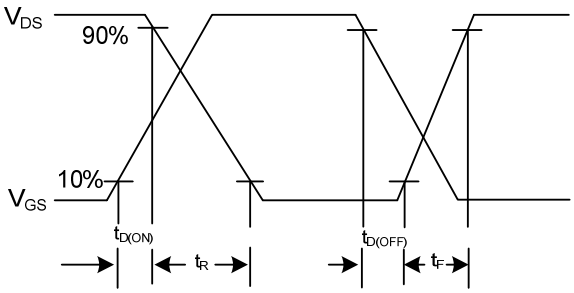


Peak Diode Recovery dv/dt Waveforms

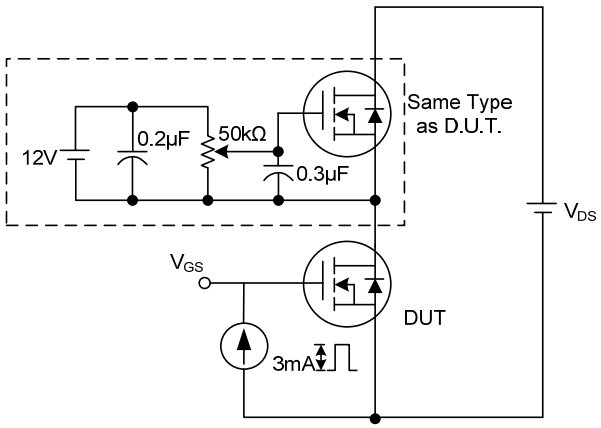
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



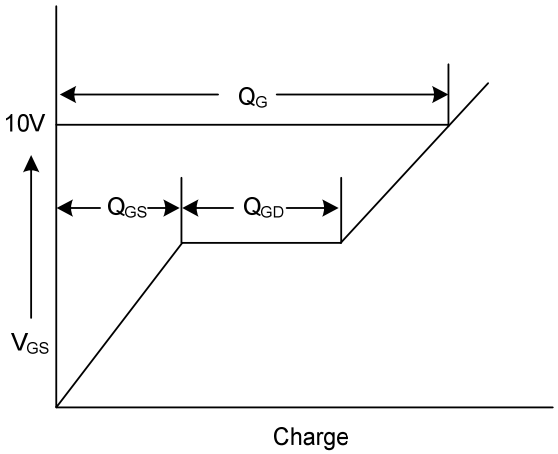
Switching Test Circuit



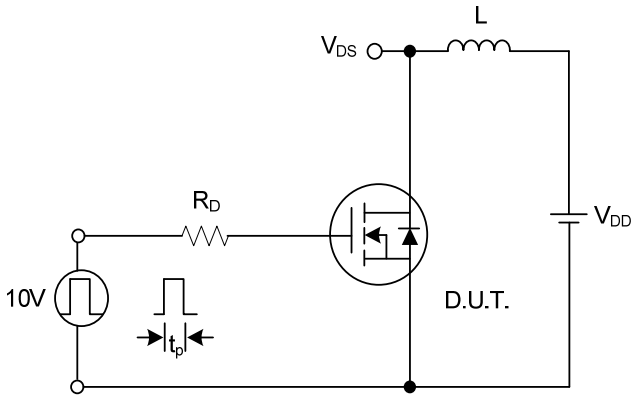
Switching Waveforms



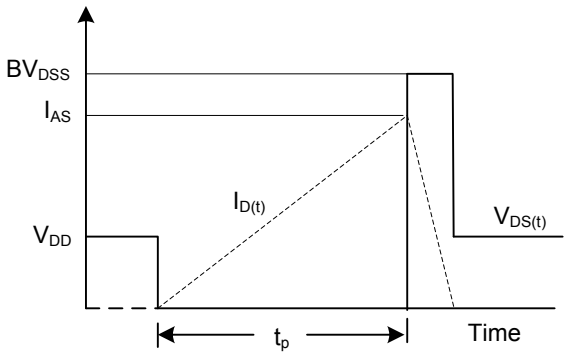
Gate Charge Test Circuit



Gate Charge Waveform



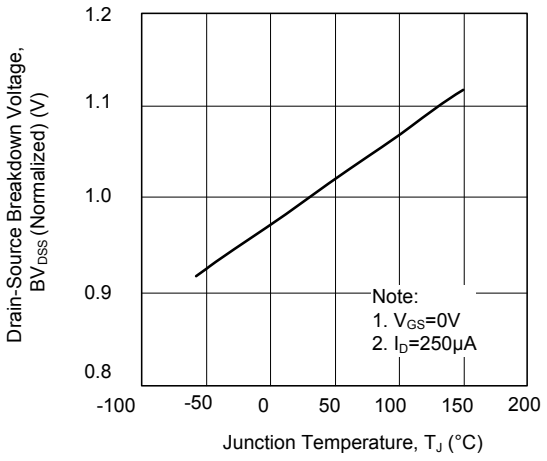
Unclamped Inductive Switching Test Circuit



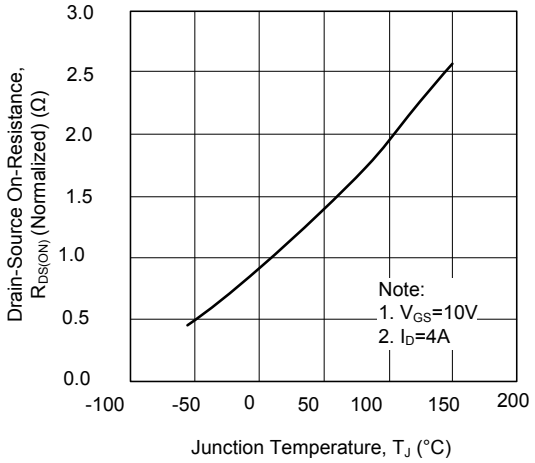
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

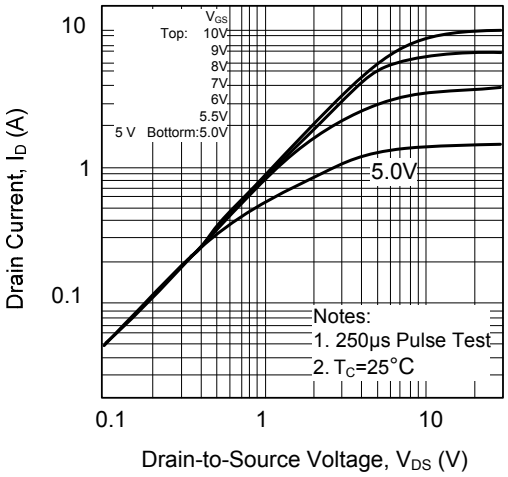
Breakdown Voltage Variation vs. Temperature



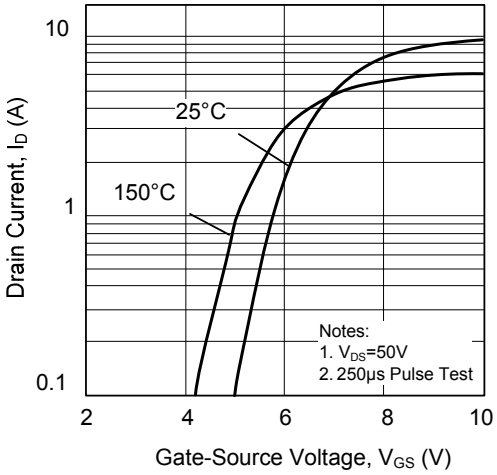
On-Resistance Junction Temperature



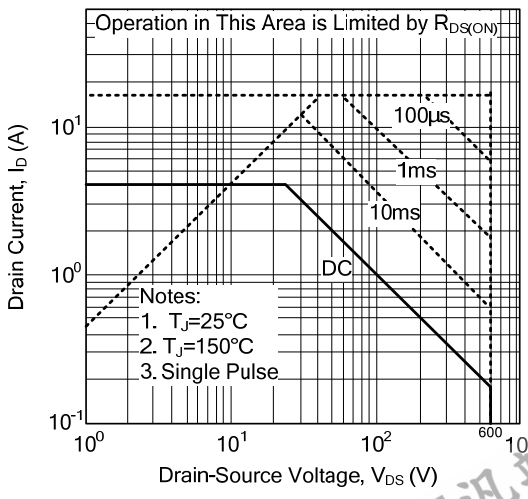
On-State Characteristics



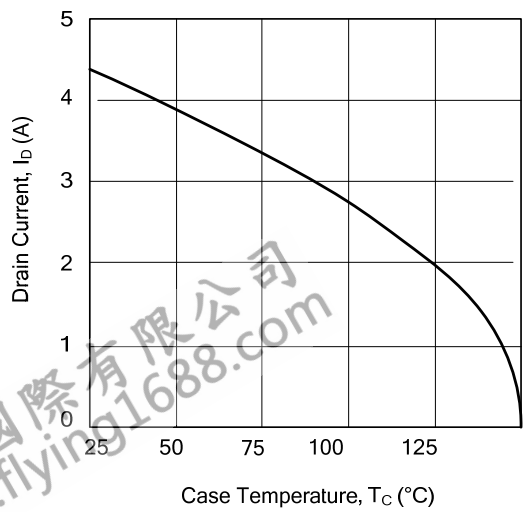
Transfer Characteristics



Safe Operating Area

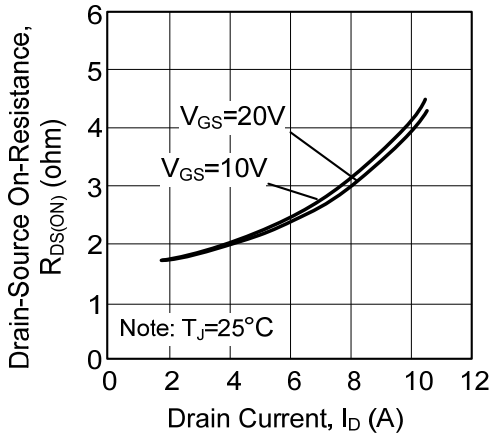


Maximum Drain Current vs. Case Temperature

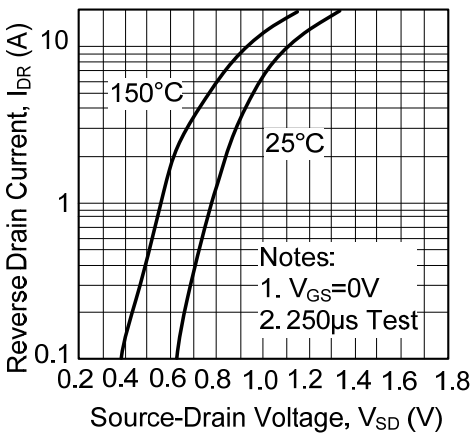


■ TYPICAL CHARACTERISTICS(Cont.)

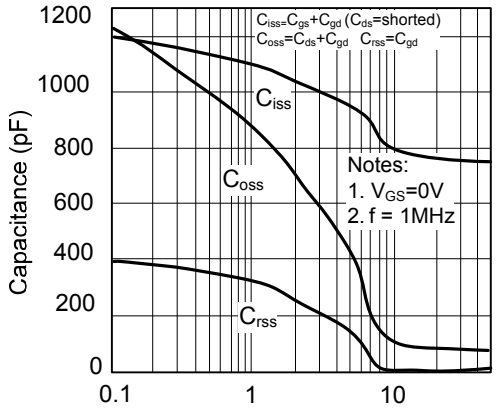
On-Resistance Variation vs. Drain Current and Gate Voltage



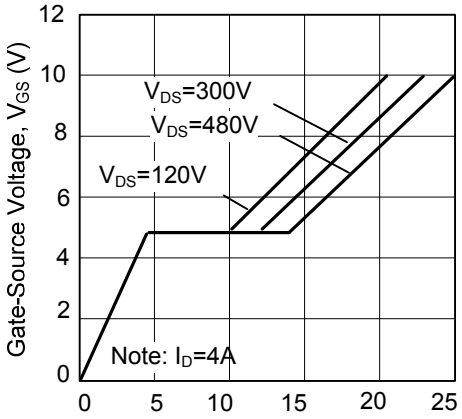
On State Current vs. Allowable Case Temperature



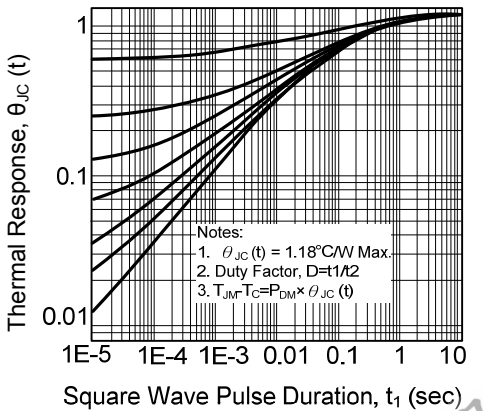
Capacitance Characteristics (Non-Repetitive)



Gate Charge Characteristics



Transient Thermal Response Curve



Power Dissipation